SEMICONDUCTOR DEVICE AND ITS MANUFACTURING METHOD

ABSTRACT OF THE DISCLOSURE

Ball Grid Array type semiconductor package is disclosed. A semiconductor chip is mounted through an adhesive material on a surface of a flexible film substrate. The plural of bump electrode are arranged in array to the opposite side of said substrate and the semiconductor chip is sealed by resin.

Concretely, an insulation layer is formed to cover an electric conductor layer pattern formed on the surface of the substrate, and the semiconductor chip is mounted through an adhesive material on the insulation layer.

The above insulation layer is divided into the plural number of part that is mutually discontinuous in the area under the above semiconductor chip. By this divided insulation layer, the short circuit between above semiconductor chip and above electric conductor layer pattern is prevented and the deformation of the substrate that comprises the above flexible films is suppressed.

Figure 1